

Automotive MOSFET

OptiMOS™ 7 Power-Transistor



Features

- OptiMOS™ power MOSFET for automotive applications
- N-channel – Enhancement mode – Logic Level
- Extended qualification beyond AEC-Q101
- Enhanced electrical testing
- Robust design
- MSL1 up to 260°C peak reflow
- 175°C operating temperature
- RoHS compliant
- 100% Avalanche tested

Potential Applications

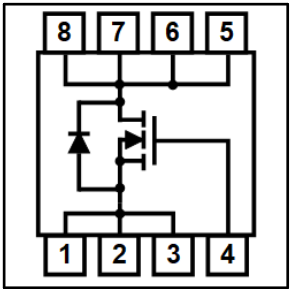
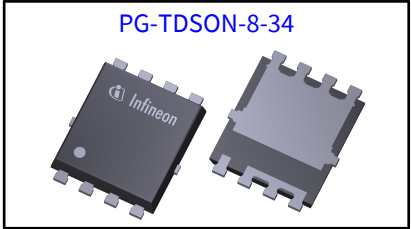
General automotive applications.

Product Validation

Qualified for automotive applications. Product validation according to AEC-Q101.

Product Summary

V_{DS}	80	V
$R_{DS(on)}$	3.3	mΩ
I_D (chip limited)	130	A



Type	Package	Marking
IAUCN08S7L033	PG-TDSON-8-34	7N08L033

Table of Contents

Description 1

Maximum ratings 3

Thermal characteristics..... 4

Electrical characteristics..... 4

Electrical characteristics diagrams..... 6

Package outline & footprint 10

Revision history..... 11

Disclaimer..... 12

Maximum Ratings

at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value	Unit
Continuous drain current	I_D	$V_{GS} = 10\text{ V}$, Chip limitation ^{1,2)}	130	A
		$V_{GS} = 10\text{ V}$, DC current	120	
		$T_a = 100^\circ\text{C}$, $V_{GS} = 10\text{ V}$, R_{thJA} on 2s2p ^{2,3)}	20	
Pulsed drain current ²⁾	$I_{D,pulse}$	$T_C = 25^\circ\text{C}$, $t_p = 100\text{ }\mu\text{s}$	356	
Avalanche energy, single pulse ²⁾	E_{AS}	$I_D = 44\text{ A}$	65.9	mJ
Avalanche current, single pulse	I_{AS}	–	87	A
Gate source voltage	V_{GS}	–	± 16	V
		Limited to duty factor of 1%	+20	
Power dissipation	P_{tot}	$T_C = 25^\circ\text{C}$	118	W
Operating and storage temperature	T_j, T_{stg}	–	-55 ... +175	$^\circ\text{C}$

Thermal Characteristics²⁾

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Thermal resistance, junction - case	R_{thJC}	–	–	–	1.3	K/W
Thermal resistance, junction - ambient ³⁾	R_{thJA}	–	–	26.2	–	

Electrical Characteristics

at $T_j = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	

Static Characteristics

Drain-source breakdown voltage	$V_{(Br)DSS}$	$V_{GS} = 0\text{ V}$, $I_D = 1\text{ mA}$	80	–	–	V
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 48\text{ }\mu\text{A}$	1.2	1.6	2.0	
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 80\text{ V}$, $V_{GS} = 0\text{ V}$, $T_j = 25^\circ\text{C}$	–	–	1	μA
		$V_{DS} = 80\text{ V}$, $V_{GS} = 0\text{ V}$, $T_j = 100^\circ\text{C}^{2)}$	–	–	12	
Gate-source leakage current	I_{GSS}	$V_{GS} = 16\text{ V}$, $V_{DS} = 0\text{ V}$	–	–	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	$V_{GS} = 4.5\text{ V}$, $I_D = 60\text{ A}$	–	3.6	4.6	m Ω
		$V_{GS} = 10\text{ V}$, $I_D = 60\text{ A}$	–	3.0	3.3	
Gate resistance ²⁾	R_G	–	–	1.1	–	Ω

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic Characteristics ²⁾						
Input capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 40 V, f = 1 MHz	–	2708	3521	pF
Output capacitance	C _{oss}		–	1055	1372	
Reverse transfer capacitance	C _{rss}		–	15	23	
Turn-on delay time	t _{d(on)}	V _{DD} = 40 V, V _{GS} = 10 V, I _D = 60 A, R _G = 3.5 Ω	–	6.1	–	ns
Rise time	t _r		–	5.9	–	
Turn-off delay time	t _{d(off)}		–	31.3	–	
Fall time	t _f		–	14.0	–	

Gate Charge Characteristics²⁾

Gate to source charge	Q_{gs}	$V_{DD} = 40\text{ V}, I_D = 60\text{ A},$ $V_{GS} = 0\text{ to }10\text{ V}$	–	8.1	10.6	nC
Gate to drain charge	Q_{gd}		–	6.5	9.9	
Gate charge total	Q_g		–	44.3	57.6	
Gate plateau voltage	$V_{plateau}$		–	3.0	–	V

Reverse Diode

Diode continuous forward current ²⁾	I_S	$T_C = 25^\circ\text{C}$	–	–	120	A
Diode pulse current ²⁾	$I_{S,pulse}$	$T_C = 25^\circ\text{C}, t_p = 100\ \mu\text{s}$	–	–	356	
Diode forward voltage	V_{SD}	$V_{GS} = 0\text{ V}, I_F = 60\text{ A}, T_j = 25^\circ\text{C}$	–	0.9	1.0	V
Reverse recovery time ²⁾	t_{rr}	$V_R = 40\text{ V}, I_F = 50\text{ A}$ $di_F/dt = 100\text{ A}/\mu\text{s}$	–	26	39	ns
Reverse recovery charge ²⁾	Q_{rr}		–	11	22	nC

¹⁾ Practically the current is limited by the overall system design including the customer-specific PCB.

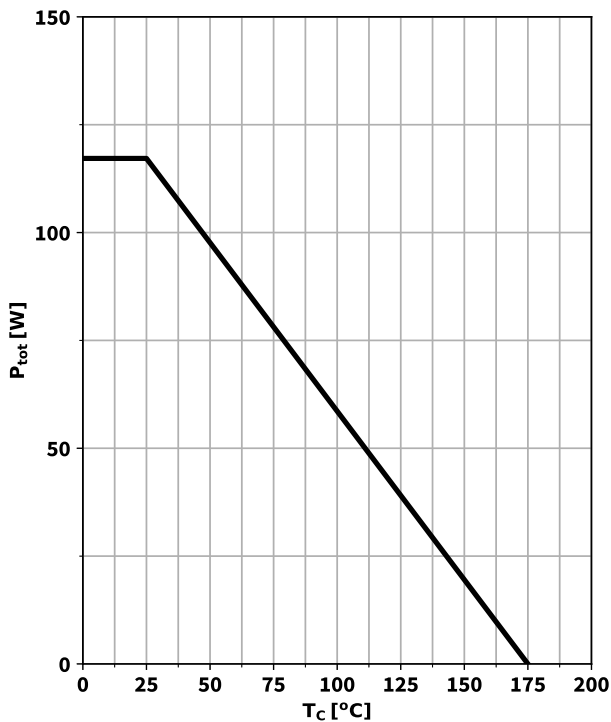
²⁾ The parameter is not subject to production testing – specified by design.

³⁾ Device on 2s2p FR4 PCB defined in accordance with JEDEC standards (JESD51-5, -7). PCB is vertical in still air.

Electrical characteristics diagrams

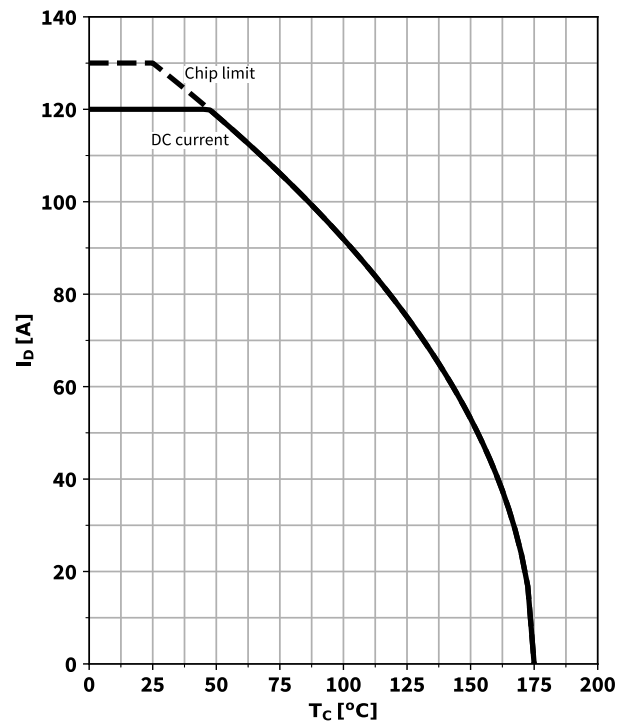
1 Power dissipation

$$P_{\text{tot}} = f(T_C); V_{\text{GS}} \geq 6 \text{ V}$$



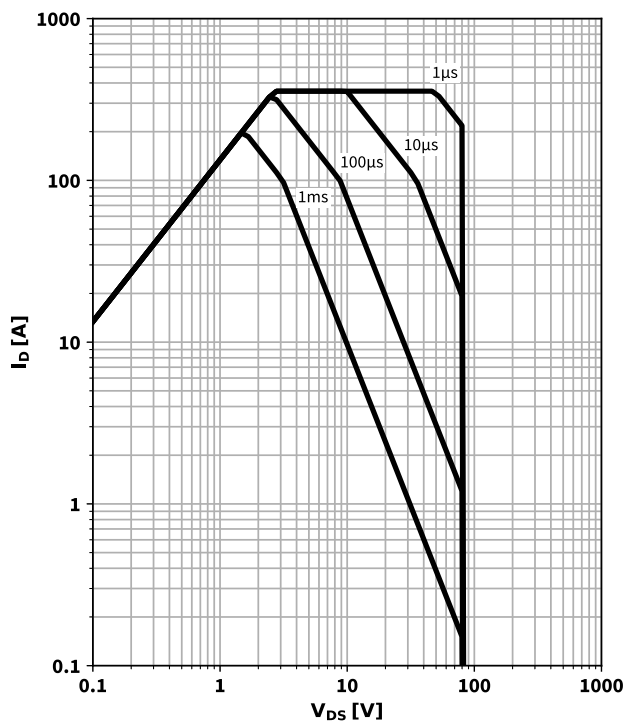
2 Drain current

$$I_D = f(T_C); V_{\text{GS}} \geq 6 \text{ V}$$



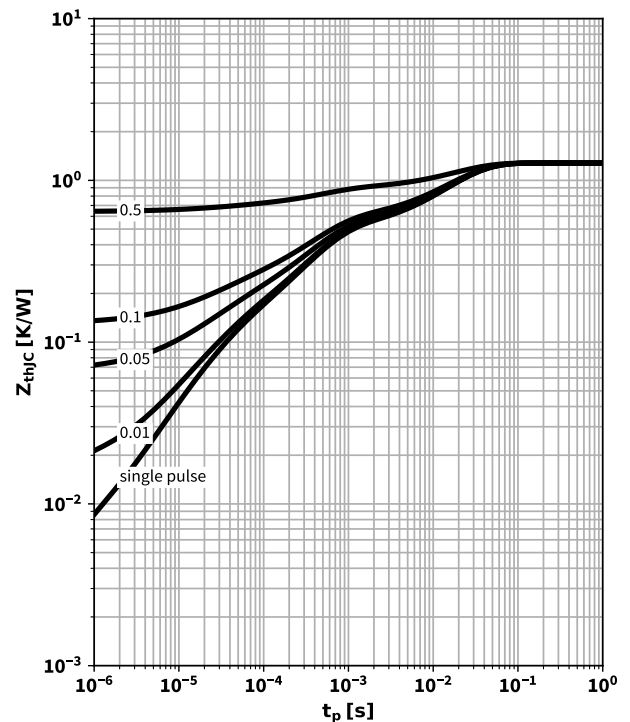
3 Safe operating area

$$I_D = f(V_{\text{DS}}); T_C = 25^{\circ}\text{C}; D = 0; \text{parameter: } t_p$$



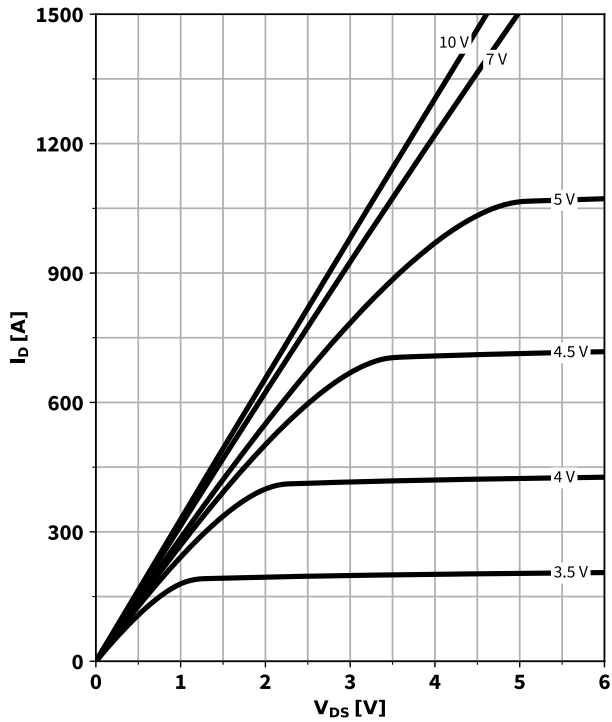
4 Max. transient thermal impedance

$$Z_{\text{thJC}} = f(t_p); \text{parameter: } D = t_p/T$$



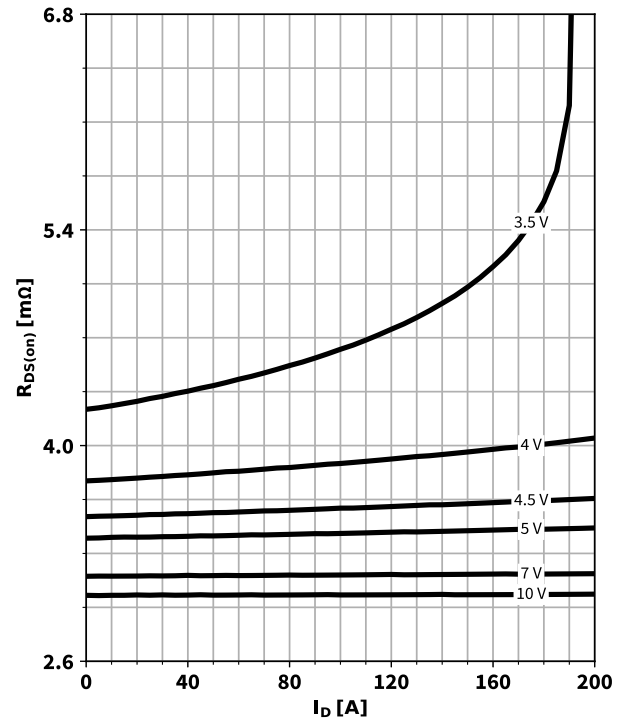
5 Typ. output characteristics

$I_D = f(V_{DS}); T_j = 25^\circ\text{C}; \text{parameter: } V_{GS}$



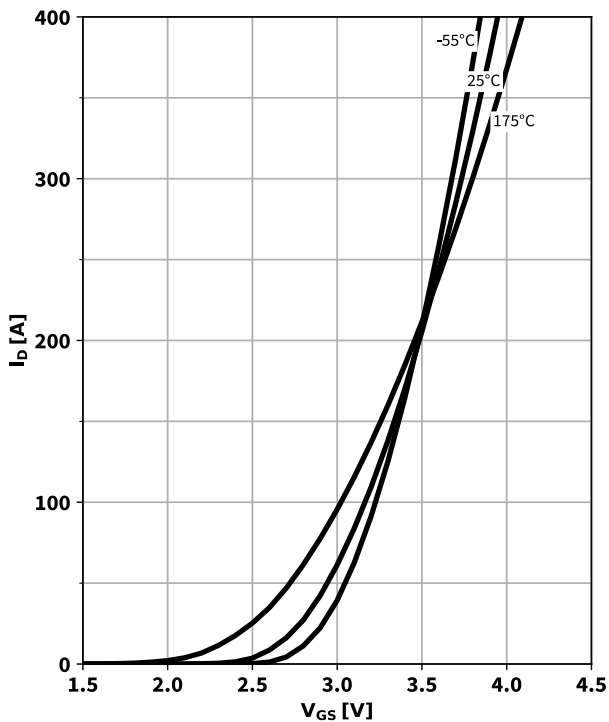
6 Typ. drain-source on-state resistance

$R_{DS(on)} = f(I_D); T_j = 25^\circ\text{C}; \text{parameter: } V_{GS}$



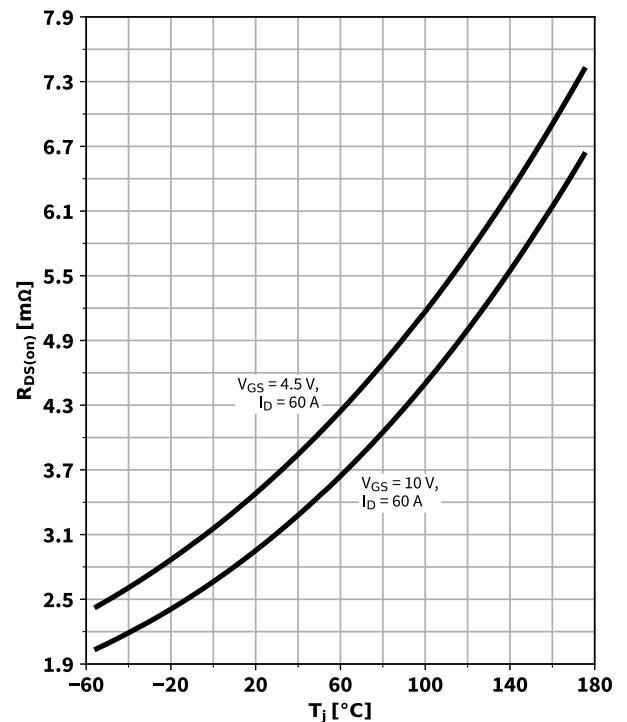
7 Typ. transfer characteristics

$I_D = f(V_{GS}); V_{DS} = 6\text{ V}; \text{parameter: } T_j$



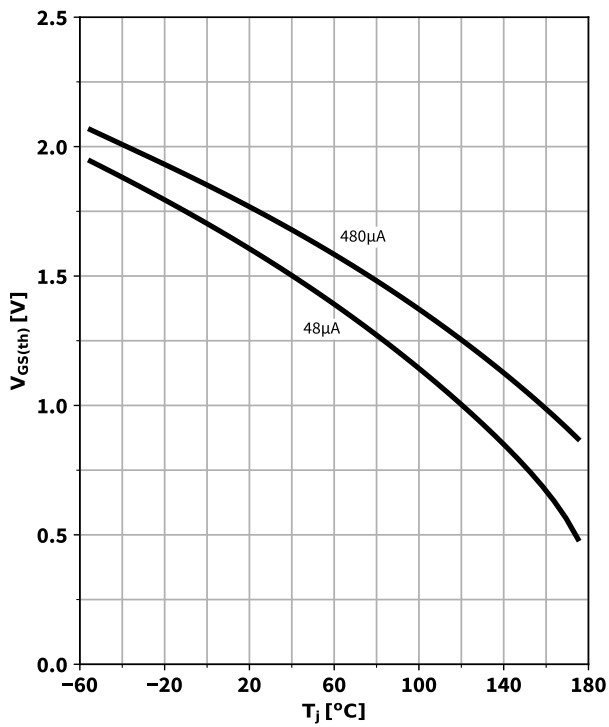
8 Typ. drain-source on-state resistance

$R_{DS(on)} = f(T_j); \text{parameter: } I_D, V_{GS}$



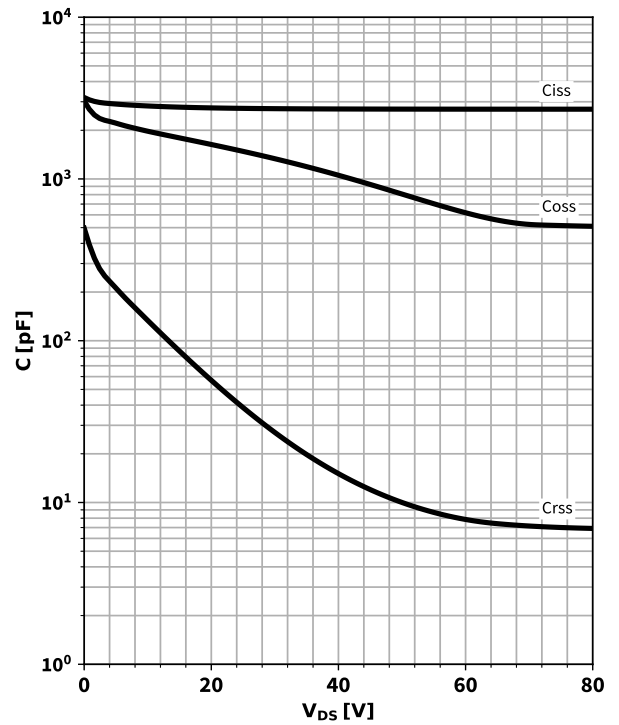
9 Typ. gate threshold voltage

$V_{GS(th)} = f(T_j)$; $V_{GS} = V_{DS}$; parameter: I_D



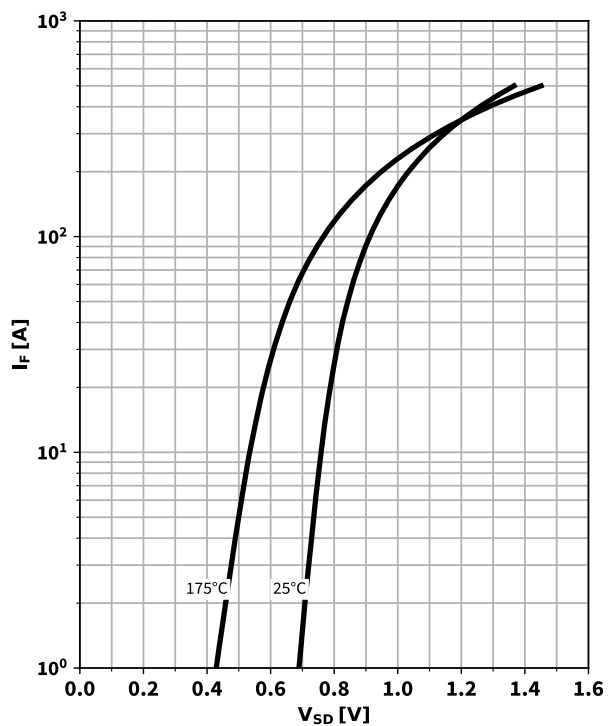
10 Typ. capacitances

$C = f(V_{DS})$; $V_{GS} = 0 V$; $f = 1 MHz$



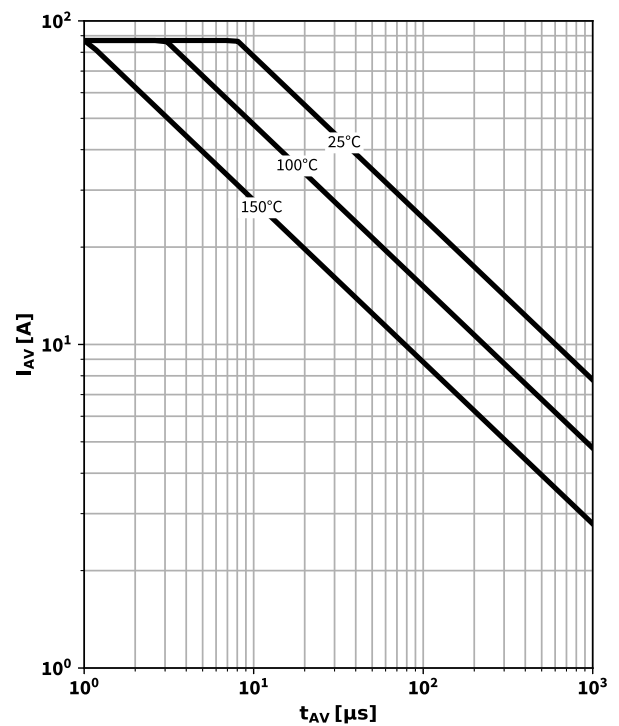
11 Typ. forward diode characteristics

$I_F = f(V_{SD})$; parameter: T_j



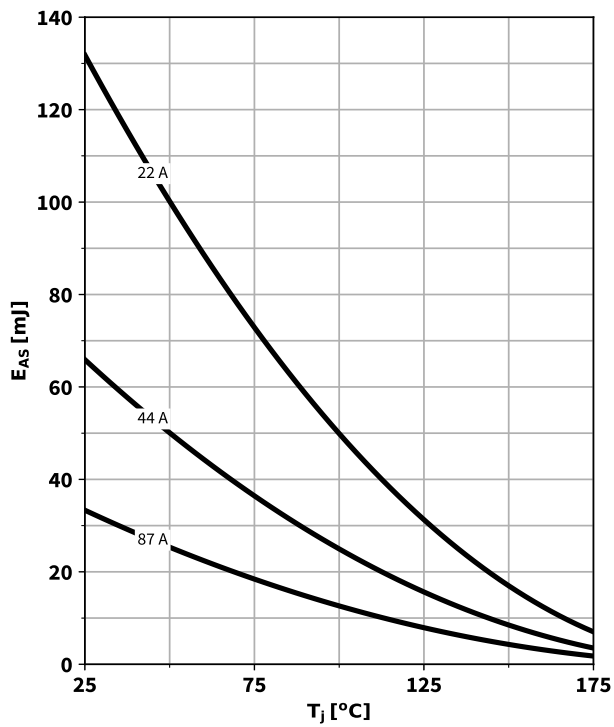
12 Typ. avalanche characteristics

$I_{AS} = f(t_{AV})$; parameter: $T_{j(start)}$



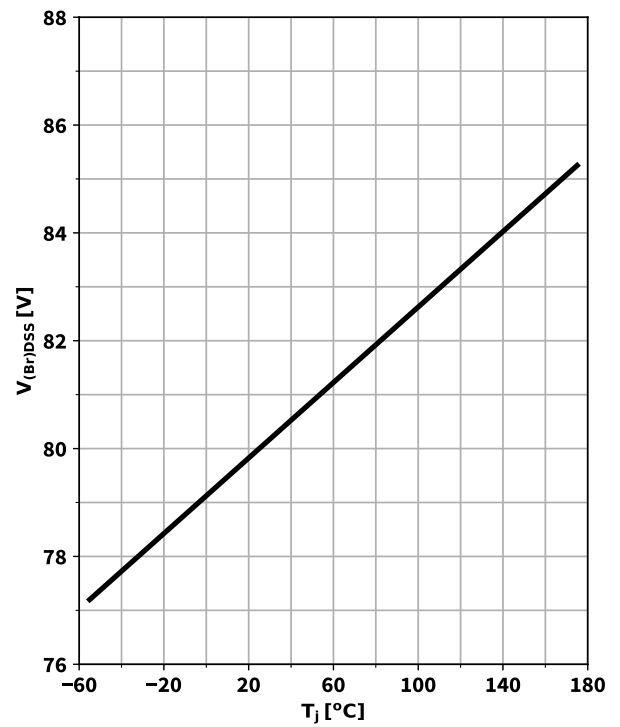
13 Typical avalanche energy

$E_{AS} = f(T_j)$; parameter: I_D



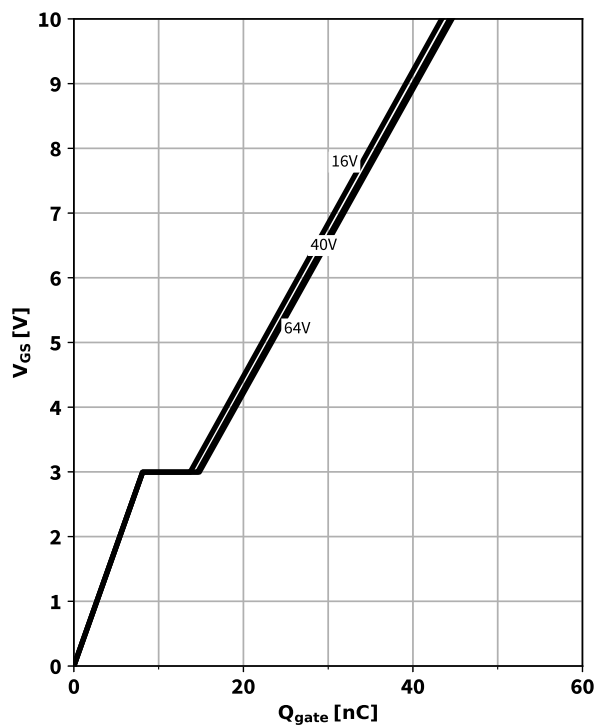
14 Drain-source breakdown voltage

$V_{(BR)DSS} = f(T_j)$; $I_D = 1$ mA

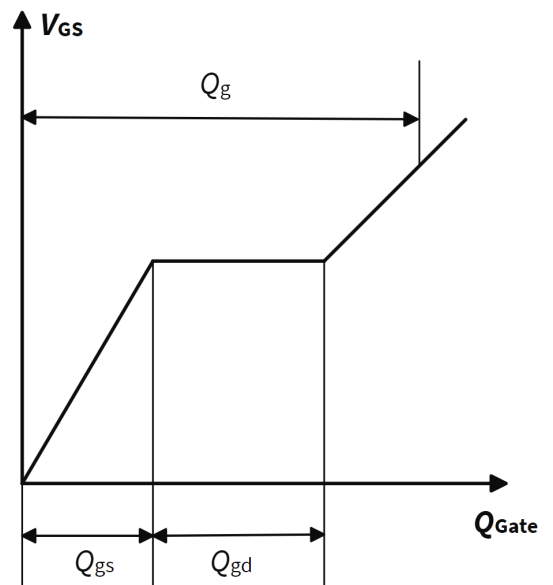


15 Typ. gate charge

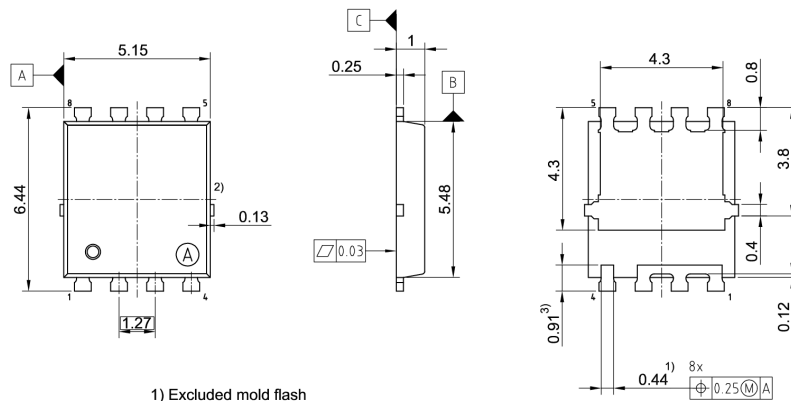
$V_{GS} = f(Q_{gate})$; $I_D = 60$ A pulsed; parameter: V_{DD}



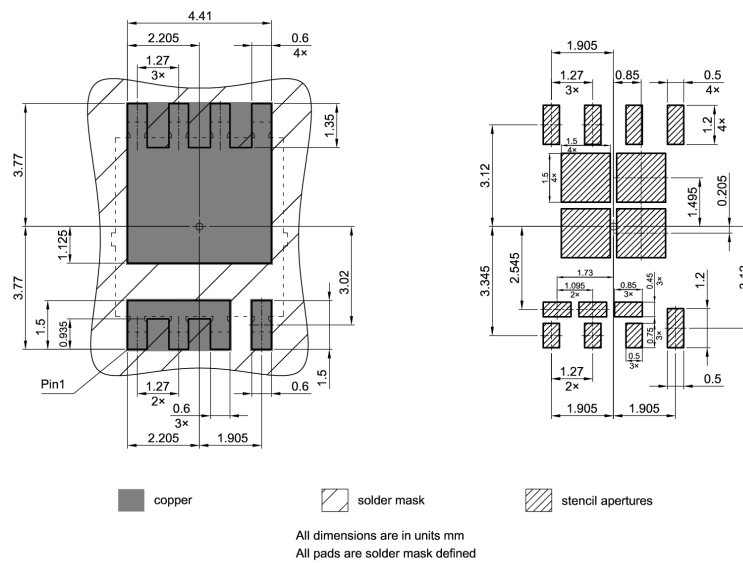
16 Gate charge waveforms



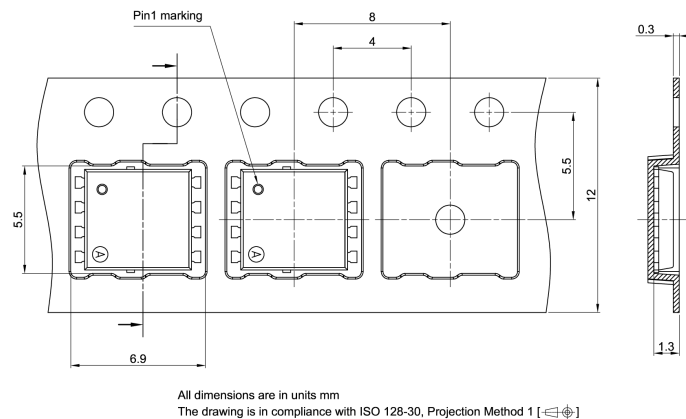
Package Outline



Footprint



Packaging



Revision History

Revision	Date	Changes
Revision 1.0	2025-04-02	Final data sheet

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for [MOSFETs](#) category:

Click to view products by [Infineon](#) manufacturer:

Other Similar products are found below :

[MCH3443-TL-E](#) [MCH6422-TL-E](#) [PMV32UP215](#) [NTNS3A92PZT5G](#) [2SK2464-TL-E](#) [2SK3818-DL-E](#) [2SJ277-DL-E](#) [2SK2267\(Q\)](#)
[AON6932A](#) [TS19452CS RL](#) [EFC2J004NUZTDG](#) [743-9](#) [US6M2GTR](#) [IRF40H233XTMA1](#) [STU5N65M6](#) [DMN13M9UCA6-7](#)
[STU7N60DM2](#) [2N7002W-G](#) [NTMFS006N08MC](#) [NTTFS5C680NLTAG](#) [IPB45P03P4L11ATMA2](#) [NVTFS6H880NLWFTAG](#)
[NTMC083NP10M5L](#) [NTTFS022N15MC](#) [NVMFS5C420NLWFT1G](#) [BXP4N65F](#) [BXP2N20L](#) [BXP2N65D](#) [NTD5C632NLT4G](#)
[NTMYS2D1N04CLTWG](#) [NVD360N65S3T4G](#) [NVMTS1D1N04CTXG](#) [CJAC130SN06L](#) [HSBA6054](#) [HSBB6054](#) [HSBB0210](#) [HSBB0056](#)
[HSBA6901](#) [BSC004NE2LS5](#) [BSZ075N08NS5](#) [LBSS138DW1T1G](#) [AP0903G](#) [SSM10N954L,EFF\(S](#) [2SK3878\(STA1,E,S\)](#)
[TPN6R303NC,LQ\(S](#) [AP3N5R0MT](#) [AP6NA3R2MT](#) [AP3C023AMT](#) [AP6242](#) [HSBB3909](#)